	TYPICAL MAXIMUM	TYPICAL			
TYPE	CLOCK FREQUENCY	POWER DISSIPATI			
′95A	36 MHz	195 mW			
LS95B	36 MHz	65 mW			

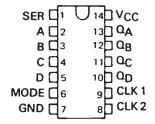
description

These 4-bit registers feature parallel and serial inputs, parallel outputs, mode control, and two clock inputs. The registers have three modes of operation:

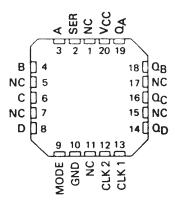
Parallel (broadside) load Shift right (the direction Q_{Δ} toward Q_{D}) Shift left (the direction QD toward QA)

Parallel loading is accomplished by applying the four bits of data and taking the mode control input high. The data is loaded into the associated flip-flops and appears at the outputs after the high-to-low transition of the clock-2 input. During loading, the entry of serial data is inhibited.

Shift right is accomplished on the high-to-low transition of clock 1 when the mode control is low; shift left is accomplished on the high-to-low transition of clock 2 when the mode control is high by connecting the output of each flip-flop to the parallel input of the previous flip-flop (QD to input C, etc.) and serial data is entered at input D. The clock input may be applied commonly to clock 1 and clock 2 if both modes can be clocked from the same source. Changes at the mode control input should normally be made while both clock inputs are low; however, conditions described in the last three lines of the function table will also ensure that register contents are protected. SN5495A, SN54LS95B . . . J OR W PACKAGE SN7495A . . . N PACKAGE SN74LS95B . . . D OR N PACKAGE (TOP VIEW)



SN54LS95B . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE

	INPUTS								OUT	PUTS	
MODE	CLOCKS		CERIAL		PARALLEL			0.0	α _C	α_{D}	
CONTROL	2 (L)	1 (R)	SERIAL	Α	В	С	D	Q _A	ΩB	<u> </u>	ω _D
Н	н	Х	Х	Х	Х	Х	х	QAO	Q_{BO}	σ_{C0}	σ^{DO}
н	1	X	x	a	ь	С	d	а	b	С	d
H	1 +	X	×	QBt	Q _C †	QDt	d	Q _{Bn}	a_{Cn}	a_{Dn}	d
L	L	н	×	×	X	X	X	QAO	σ_{BO}	σ_{CO}	σ_{DO}
L	×	‡	н	х	Х	X	X	н	Q_{An}	QBn	σ_{Cu}
L	×	1	L	х	X	X	X	L	Q_{An}	QBn	a_{Cn}
†	L	L	×	X	Х	X	X	QAO	Q_{BO}	a_{co}	Q_{DO}
4	L	L	×	х	X	X	X	QAO	Q_{BO}	a_{C0}	a_{DO}
4	L	н	×	х	X	×	X	QAO	Q _{BO}	a_{C0}	σ_{DO}
†	н	L	×	x	X	×	×	QAO	Q_{BO}	a_{C0}	σ_{DO}
†	Н	н	×	x	Х	X	X	QAO	QBO	a_{C0}	σ_{DO}

†Shifting left requires external connection of Q_B to A, Q_C to B, and Q_D to C. Serial data is entered at input D. H = high level (steady state), L = low level (steady state), X = irrelevant (any input, including transitions)

1 = transition from high to low level, 1 = transition from low to high level

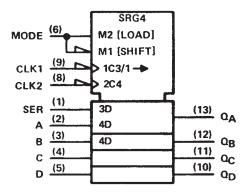
a, b, c, d = the level of steady-state input at inputs A, B, C, or D, respectively.

 Q_{A0} , Q_{B0} , Q_{C0} , Q_{D0} = the level of Q_{A} , Q_{B} , Q_{C} , or Q_{D} , respectively, before the indicated steady-state input conditions were established.

 Q_{An} , Q_{Bn} , Q_{Cn} , Q_{Dn} = the level of Q_{A} , Q_{B} , Q_{C} , or Q_{D} , respectively, before the most-recent \downarrow transition of the clock.

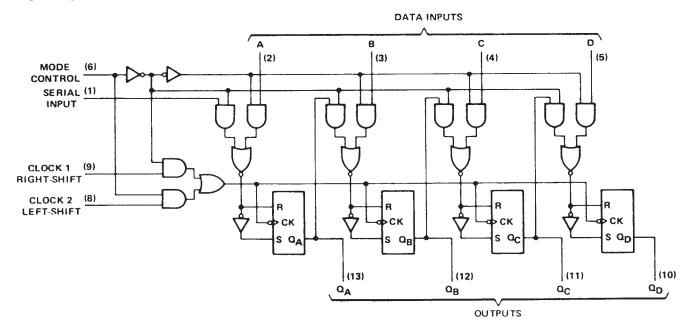


logic symbol†



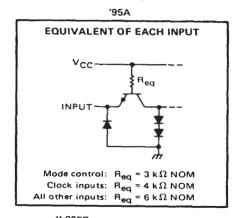
 $^{^\}dagger$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

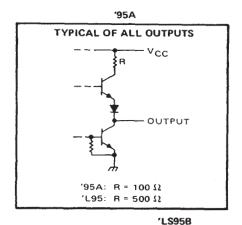
logic diagram (positive logic)

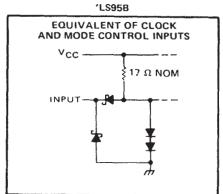


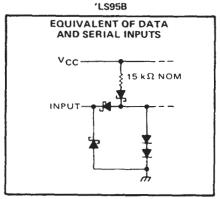


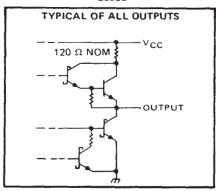
schematics of inputs and outputs











absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

	SN54'	SN54LS'	SN74'	SN74LS'	UNIT
Supply voltage, V _{CC} (see Note 1)	7	7	7	7	V
Input voltage	5.5	7	5.5	7	V
Interemitter voltage (see Note 2)	5.5		5.5		V
Operating free-air temperature range	- 55	to 125	0	to 70	°C
Storge temperature range	- 65	to 150	- 65	to 150	°C

- NOTES: 1. Voltage values, except interemitter voltage, are with respect to network ground terminal.
 - 2. This is the voltage between two emitters of a multiple-emitter input transistor. This rating applies between the clock-2 input and the mode control input of the '95A.

recommended operating conditions

	SN5495A		SN7495A			UNIT	
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC	4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH			-800			-800	μΑ
Low-level output current, IOL			16			16	mA
Clock frequency, f _{clock}	0		25	0		25	MHz
Width of clock pulse, tw(clock) (See Figure 1)	20			20			กร
Setup time, high-level or low-level data, t _{su} (See Figure 1)	15			15			กร
Hold time, high-level or low-level data, th (See Figure 1)	0			0			ns
Time to enable clock 1, tenable 1 (See Figure 2)	15			15			ns
Time to enable clock 2 (See Figure 2)	15			15			กร
Time to inhibit clock 1, tinhibit 1 (See Figure 2)	5			5			กร
Time to inhibit clock 2, tinhibit 2 (See Figure 2)	5			5			ns
Operating free-air temperature, TA	55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER				SN5495A			SN7495A			
		TEST CONDITIONS [†]	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT	
VIH	High-level input volta	ige		2			2			V
VIL	Low-level input volta	ge				0.8			0.8	٧
VIK	Input clamp voltage		V _{CC} = MIN, I _I = -12 mA	<u> </u>		-1.5			-1.5	V
	44.4		V _{CC} = MIN, V _{IH} = 2 V,	2.4	3.4		2.4	3.4		V
VOH High-level output voltage		tage	$V_{1L} = 0.8 \text{ V}, I_{OH} = -800 \mu\text{A}$	2.4	3.4		2.4	3.4		ľ
			V _{CC} = MIN, V _{IH} = 2 V,			0.4		0.2	0.4	v
VOL Low-level outp	Low-level output vol	tage	V _{1L} = 0.8 V, I _{OL} = 16 mA	0.2		0.4		0.2	0.4	
l _l	Input current at maximum input volta	age	V _{CC} = MAX, V _I = 5.5 V			1			1	mA
hн	High-level	Serial, A, B, C, D, Clock 1 or 2	V _{CC} = MAX, V ₁ = 2.4 V			40		-	40	μА
111	input current	Mode control	90			80			80	1
1	Low-level	Serial, A, B, C, D, Clock 1 or 2	V MAY V = 0.4V			-1.6			-1.6	mA
IL input current	Mode control	$V_{CC} = MAX, V_1 = 0.4 V$	-		-3.2	<u> </u>		-3.2	-	
los	OS Short-circuit output current §		V _{CC} = MAX	-18		-57	-18		-57	mA
Icc			V _{CC} = MAX, See Note 3		39	63		39	63	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 3: ICC is measured with all outputs and serial input open; A, B, C, and D inputs grounded; mode control at 4.5 V; and a momentary 3 V, then ground, applied to both clock inputs.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max} Maximum clock frequency	0 - 15 - 5 . D 400 0	25	36		MHz
tPLH Propagation delay time, low-to-high-level output from clock	C _L = 15 pF, R _L = 400Ω , See Figure 1		18	27	ns
tPHL Propagation delay time, high-to-low-level output from clock	See Figure 1		21	32	ns



 $^{^{\}ddagger}$ All typical values are at VCC = 5 V, TA = 25 °C.

[§] Not more than one output should be shorted at a time.

recommended operating conditions

	SN54LS95B			SN74LS95B			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	ONLI
Supply voltage, VCC	4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH			-400			-400	μΑ
Low-level output current, IOI			4			8	mA
Clock frequency, fctock	0		25	0		25	MHz
Width of clock pulse, tw(clock) (see Figure 1)	20			20			ns
Setup time, high-level or low-level data, t _{su} (see Figure 1)	20			20			ns
Hold time, high-level or low-level data, th (see Figure 1)	20			10			ns
Time to enable clock 1, tenable 1 (see Figure 2)	20			20			ns
Time to enable clock 2, tenable 2 (see Figure 2)	20			20			ns
Time to inhibit clock 1, tinhibit 1 (see Figure 2)	20			20			ns
Time to inhibit clock 2, t _{inhibit} 2 (see Figure 2)	20			20			ns
Operating free-air temperature, TA	-55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

					SN54LS95B			SN74LS95B		
	PARAMETER	TEST CO	TEST CONDITIONS [†]			MAX	MIN	TYP [‡]	MAX	UNIT
ViH	High-level input voltage			2			2			V
VIL	Low-level input voltage					0.7			8.0	V
VIK	Input clamp voltage	V _{CC} = MIN,	$I_1 = -18 \text{ mA}$			-1.5			-1.5	V
	High-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max,	V _{IH} = 2 V, I _{OH} = -400 μA	2.5	3.4		2.7	3.4		V
	V _{OL} Low-level output voltage	V _{CC} = MIN,	IOL = 4 mA		0.25	0.4		0.25	0.4	,
VOL		V _{IH} = 2 V, V _{IL} = V _{IL} max	1 _{OL} = 8 mA					0.35	0.5	Ľ
l ₁	Input current at maximum input voltage	V _{CC} = MAX,	V ₁ = 7 V			0.1			0.1	mA
чн	High-level input current	V _{CC} = MAX,	V ₁ = 2.7 V			20			20	μА
IJĹ	Low-level	V _{CC} = MAX,	V ₁ = 0.4 V			-0.4			-0.4	mA
los	Short-circuit output current \$	V _{CC} = MAX		-20		-100	-20		-100	mA
Icc	Supply current	V _{CC} = MAX,	See Note 3		13	21		13	21	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max} Maximum clock frequency	$C_{\parallel} = 15 \text{pF}, R_{\parallel} = 2 \text{k}\Omega,$	25	36		MHz
tpLH Propagation delay time, low-to-high-level output from clock	See Figure 1		18	27	ns
tpHL Propagation delay time, high-to-low-level output from clock	Jee rigare v	<u> </u>	21	32	ns

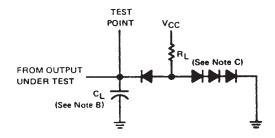


[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$.

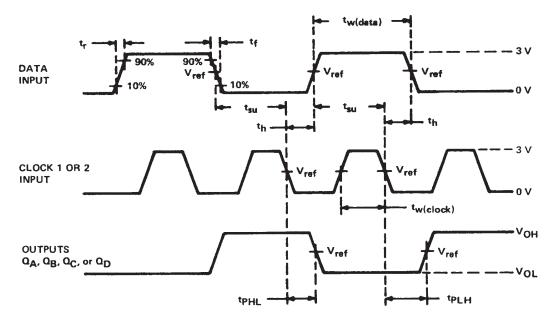
[§] Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 3: ICC is measured with all outputs and serial input open; A, B, C, and D inputs grounded; mode control at 4.5 V; and a momentary 3 V, then ground, applied to both clock inputs.

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

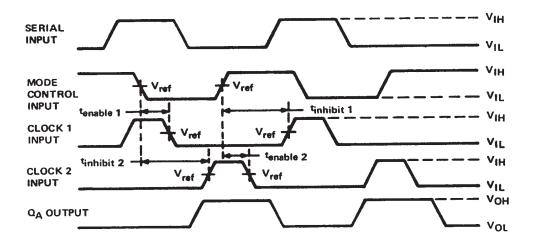


- NOTES: A. Input pulses are supplied by a generator having the following characteristics: $t_f \le 10$ ns, $t_f \le 10$ ns, and $Z_{out} \approx 50 \Omega$. For the data pulse generator, PRR = 500 kHz; for the clock pulse generator, PRR = 1 MHz. When testing f_{max} , vary PRR. For '95A, $t_{w(data)} \ge 20$ ns, $t_{w(clock)} \ge 15$ ns. For 'LS95B, $t_{w(data)} \ge 20$ ns, $t_{w(clock)} \ge 15$ ns.
 - B. C_L includes probe and jig capacitance.
 - C. All diodes are 1N3064 equivalent.
 - D. For '95A, V_{ref} = 1.5 V; for 'LS95B, V_{ref} = 1.3 V.

VOLTAGE WAVEFORMS
FIGURE 1-SWITCHING TIMES



PARAMETER MEASUREMENT INFORMATION



NOTES: A. Input is at a low level.

B. For '95A, $V_{ref} = 1.5 \text{ V}$; for 'LS958, $V_{ref} = 1.3 \text{ V}$.

VOLTAGE WAVEFORMS
FIGURE 2-CLOCK ENABLE/INHIBIT TIMES







i.com 18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN5495AJ	OBSOLETE	CDIP	J	14	TBD	Call TI	Call TI
SN7495AJ	OBSOLETE	CDIP	J	14	TBD	Call TI	Call TI
SN7495AJ	OBSOLETE	CDIP	J	14	TBD	Call TI	Call TI
SN7495AN	OBSOLETE	PDIP	N	14	TBD	Call TI	Call TI
SN7495AN	OBSOLETE	PDIP	N	14	TBD	Call TI	Call TI
SN74LS95BD	OBSOLETE	SOIC	D	14	TBD	Call TI	Call TI
SN74LS95BD	OBSOLETE	SOIC	D	14	TBD	Call TI	Call TI
SN74LS95BDR	OBSOLETE	SOIC	D	14	TBD	Call TI	Call TI
SN74LS95BDR	OBSOLETE	SOIC	D	14	TBD	Call TI	Call TI
SN74LS95BN	OBSOLETE	PDIP	N	14	TBD	Call TI	Call TI
SN74LS95BN	OBSOLETE	PDIP	N	14	TBD	Call TI	Call TI
SNJ5495AJ	OBSOLETE	CDIP	J	14	TBD	Call TI	Call TI
SNJ5495AJ	OBSOLETE	CDIP	J	14	TBD	Call TI	Call TI
SNJ5495AW	OBSOLETE	CFP	W	14	TBD	Call TI	Call TI
SNJ5495AW	OBSOLETE	CFP	W	14	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



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